



SOT189-2

plastic leaded chip carrier; 84 leads

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	PLCC84
Package type industry code	PLCC84
Package style descriptive code	PLCC (plastic leaded chip carrier)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	112E13
JEDEC package outline code	MS-018
JEITA package outline code	EDR-7319
Mounting method type	S (surface mount)
Issue date	14-11-2001

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	29.21	-	29.26	29.41	mm
E	package width	29.21	-	29.26	29.41	mm
A	seated height	4.19	-	4.57	4.57	mm
A ₂	package height	[tbd]	-	3.81	[tbd]	mm
n ₂	actual quantity of termination	-	-	84	-	



2. Package outline

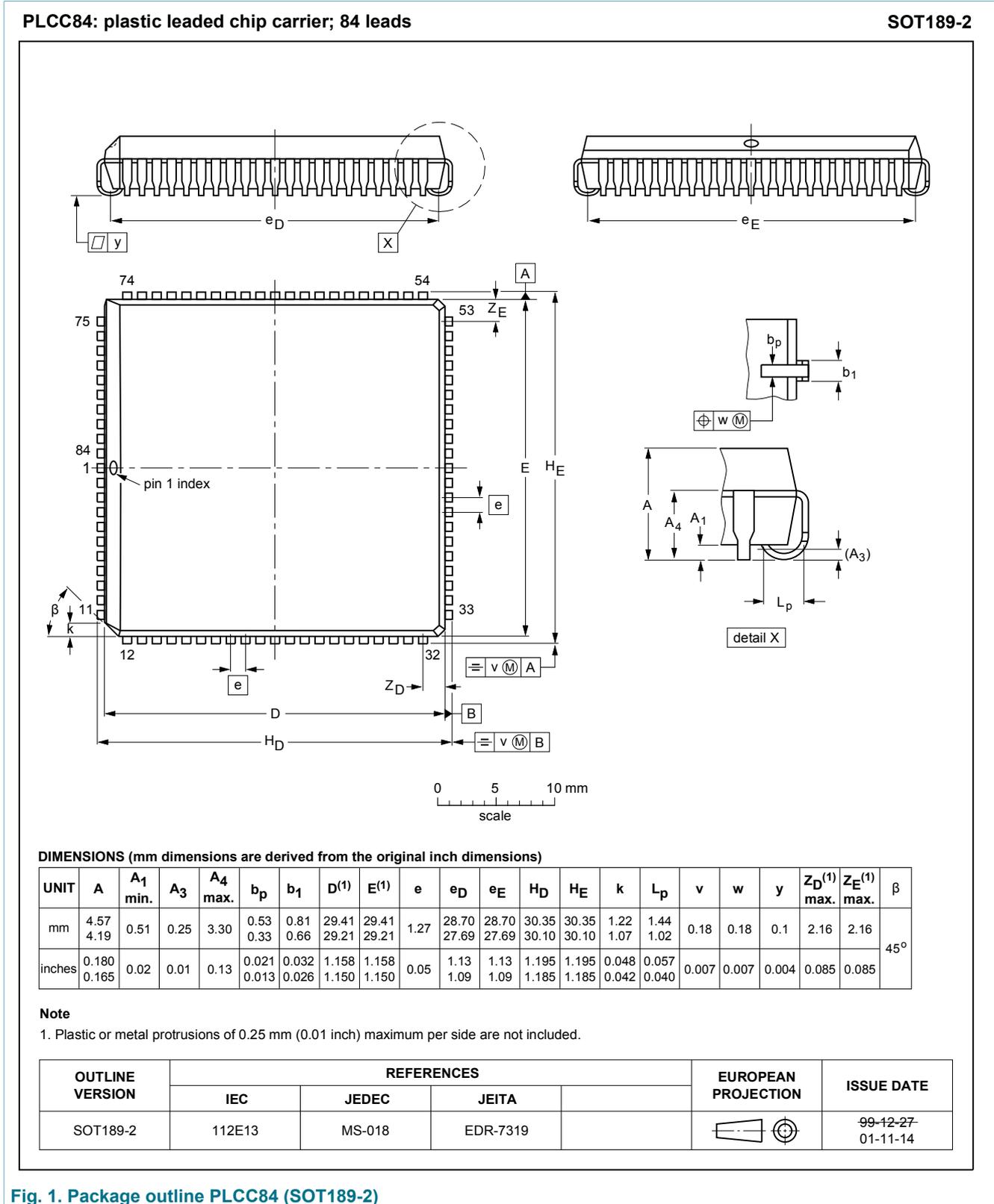


Fig. 1. Package outline PLCC84 (SOT189-2)

3. Soldering

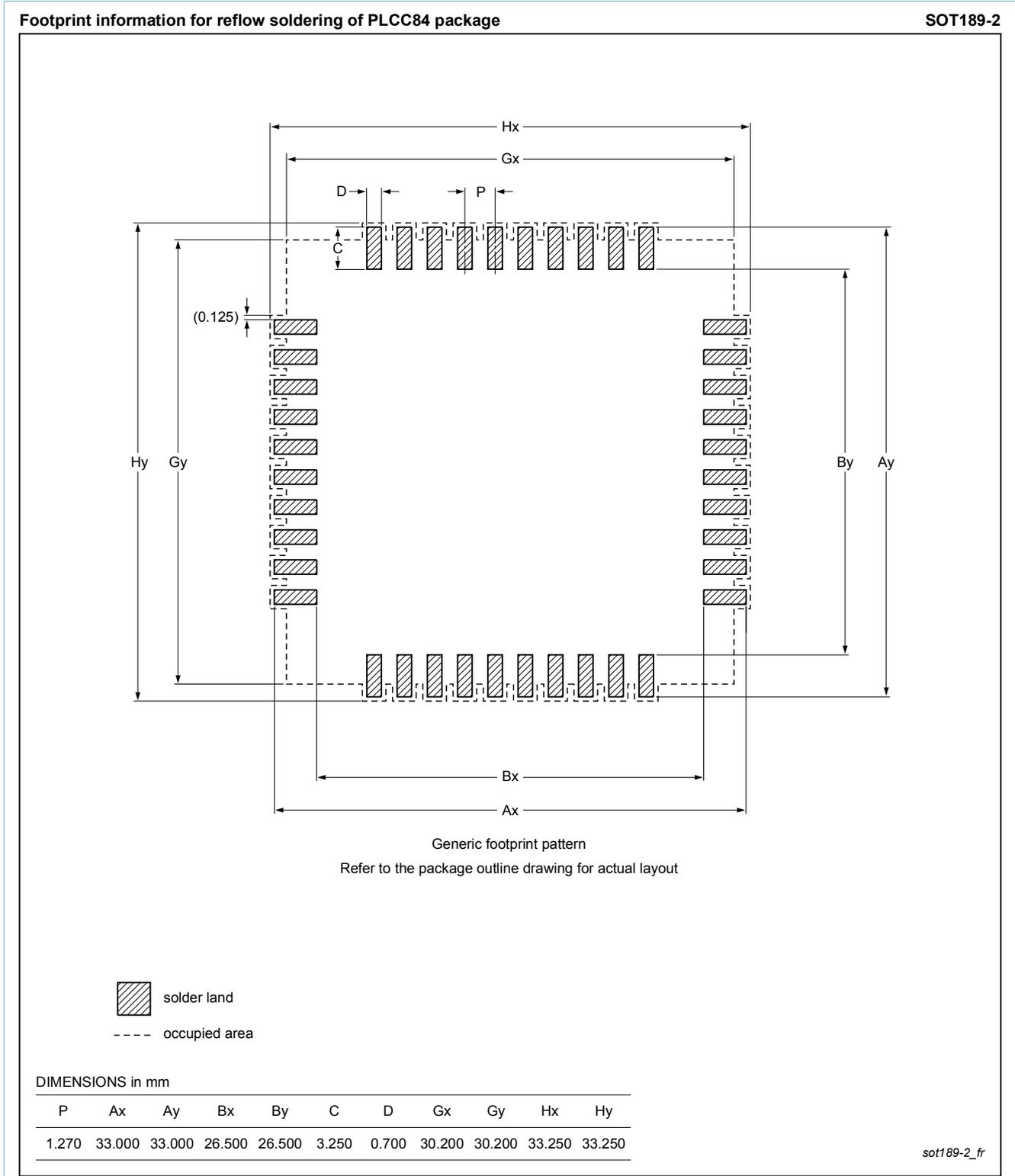


Fig. 2. Reflow soldering footprint for PLCC84 (SOT189-2)

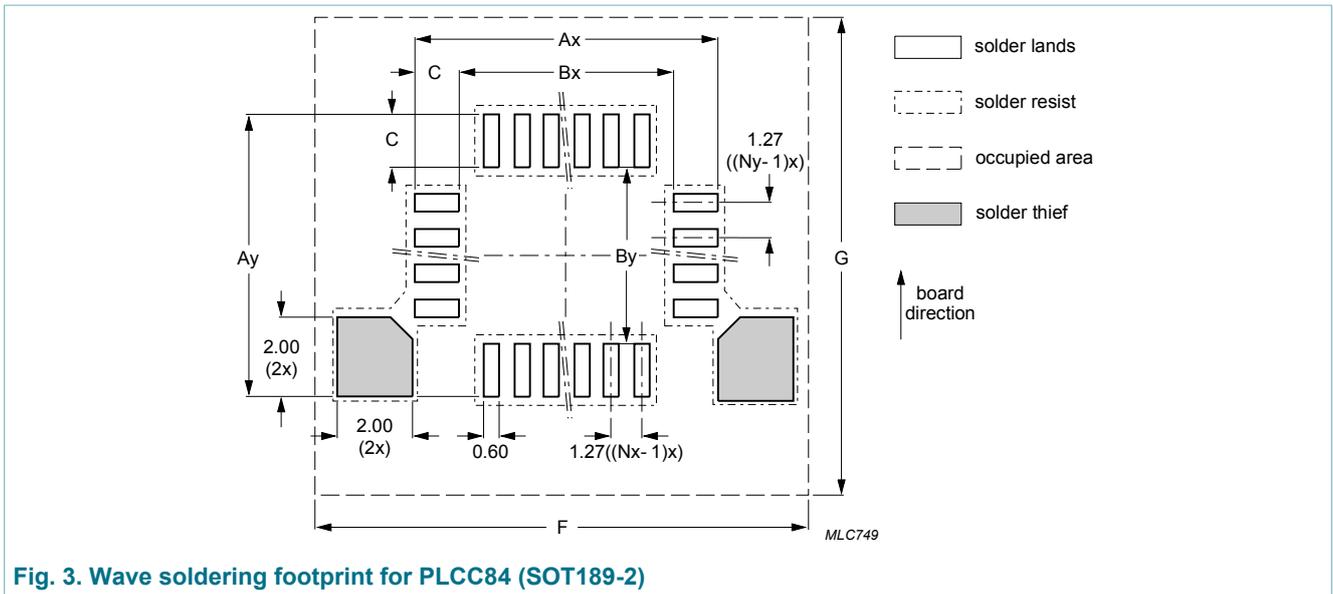


Fig. 3. Wave soldering footprint for PLCC84 (SOT189-2)

4. Legal information

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